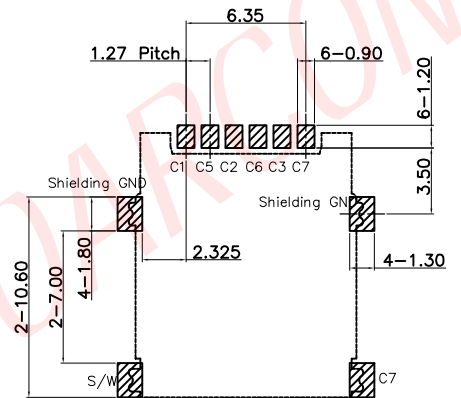
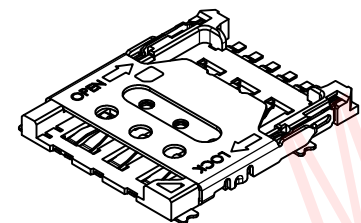
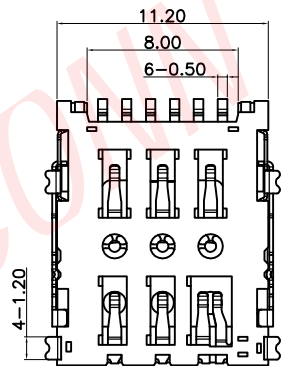
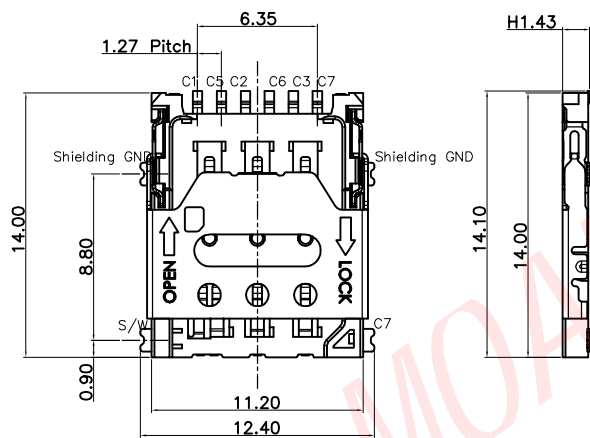
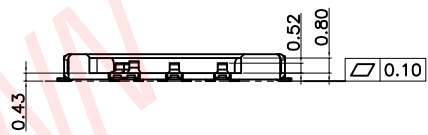


All materials, plating and process meet HF requirements.



Recommended PCB Layout (Top View)  
General Tolerance ±0.05



### Specification

#### MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.  
Contact: Copper Alloy  
SHELL: Stainless Stell

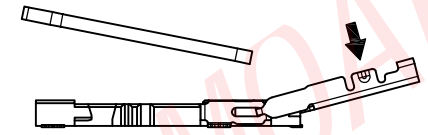
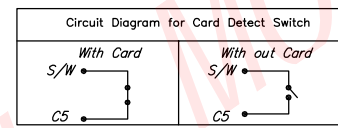
#### PLATING:

Contact: Plated 50u'' Ni Overall Contact ALL Au 1U,  
Shell: ALL NI 30U/MIN

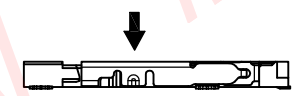
#### Electrical:

Current Rating :0.5mA AC/DC max.  
Voltage Rating :125V AC/DC  
Ambient Temperature Range :-20° C~+60° C  
Storage Temperature Range :-40° C~+70° C  
Ambient Humidity Range :95% R.H. Max.  
Contact Resistance:80m Ωmax.  
Insulation Resistance:100M Ωmin./100V DC  
Mating Cycles:5,000 Insertions  
Reflow peak temp.: 260° C ±5° C, 3~5 S

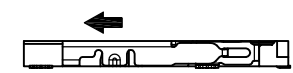
PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
S/W	SWITSH PIN



Step 1: Lift the cover and put in NanoSIM card



Step 2: Close the cover



Step 3: Push lock



DONG GUAN MOARCONN ELECTRONIC Co.,Ltd.

DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : NanoSIM 7 pin H1.43 LIFT COVER	DRAWING: Alexander	DATE: 2023.06.25
	PRODUCT NO. : NS143-T1151-01	CHECK:	DATE:
DIMENSION TOLERANCE	DRAWING NO. : D-NS143-T1151-01	APPROVED:	DATE:
X.X: ± 0.35 X.XX: ± 0.25 X.XXX: ± 0.10 ANGULAR: ± 2'	SCALE: 1:1	DWG ID: C D	REV.: X0 PAGE: 1 of 1

X0	---	NEW RELEASE	Alexander	2023.06.25
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE